

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Q1 N-CHANNEL	Q2 P-CHANNEL	Units
Drain-Source Voltage			V _{DSS}	20	-20	V
Gate-Source Voltage			V _{GSS}	±12	±12	V
Continuous Drain Current (Note 5) V _{GS} = 4.5V	Steady State	T _A = +25°C T _A = +70°C	I _D	4.7 3.8	-3.2 -2.5	A
	t < 5s	T _A = +25°C T _A = +70°C	I _D	6.1 4.9	-4.1 -3.2	A
Maximum Continuous Body Diode Forward Current (Note 5)			I _S	2	-1.5	A
Pulsed Drain Current (10μs pulse, duty cycle = 1%)			I _{DM}	30	-18	A

Thermal Characteristics

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	Steady State	P _D	1.4	W
	t < 5s		2.2	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R _{θJA}	92	°C/W
	t < 5s		55	
Thermal Resistance, Junction to Case (Note 5)		R _{θJC}	30	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to 150	°C

Electrical Characteristics Q1 N-CHANNEL (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	—	—	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	—	—	1.0	μA	V _{DS} = 20V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±10	μA	V _{GS} = ±8V, V _{DS} = 0V
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	V _{GS(th)}	0.35	—	1.4	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(on)}	—	23	40	mΩ	V _{GS} = 4.5V, I _D = 4.2A
		—	26	65		V _{GS} = 2.5V, I _D = 3.3A
Diode Forward Voltage	V _{SD}	—	0.7	1.2	V	V _{GS} = 0V, I _S = 4.4A
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C _{iss}	—	713	—	pF	V _{DS} = 10V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	—	80	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	68	—	pF	
Gate Resistance	R _g	—	15	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge (V _{GS} = 4.5V)	Q _g	—	8	—	nC	V _{DS} = 10V, I _D = 5.5A
Total Gate Charge (V _{GS} = 8V)		—	15	—	nC	
Gate-Source Charge	Q _{gs}	—	1.0	—	nC	
Gate-Drain Charge	Q _{gd}	—	1.1	—	nC	
Turn-On Delay Time	t _{D(on)}	—	3.6	—	ns	V _{DD} = 10V, V _{GS} = 4.5V, R _L = 2.3Ω, R _G = 1Ω
Turn-On Rise Time	t _r	—	15.9	—	ns	
Turn-Off Delay Time	t _{D(off)}	—	16.0	—	ns	
Turn-Off Fall Time	t _f	—	2.6	—	ns	
Body Diode Reverse Recovery Time	t _{rr}	—	6.6	—	nS	I _S = 4.4A, dI/dt = 100A/μs
Body Diode Reverse Recovery Charge	Q _{rr}	—	1.2	—	nC	I _S = 4.4A, dI/dt = 100A/μs

- Notes: 5. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.
6. Short duration pulse test used to minimize self-heating effect.
7. Guaranteed by design. Not subject to product testing.

Electrical Characteristics Q2 P-CHANNEL (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV_{DSS}	-20	—	—	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current $T_J = +25^\circ\text{C}$	I_{DSS}	—	—	-1.0	μA	$V_{DS} = -20V, V_{GS} = 0V$
Gate-Source Leakage	I_{GSS}	—	—	± 10	μA	$V_{GS} = \pm 8V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	$V_{GS(th)}$	-0.35	—	-1.4	V	$V_{DS} = V_{GS}, I_D = -250\mu A$
Static Drain-Source On-Resistance	$R_{DS(on)}$	—	59	90	m Ω	$V_{GS} = -4.5V, I_D = -2.9A$
		—	76	137		$V_{GS} = -2.5V, I_D = -2.3A$
Diode Forward Voltage	V_{SD}	—	-0.65	-1.2	V	$V_{GS} = 0V, I_S = -3.0A$
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C_{iss}	—	881	—	pF	$V_{DS} = -10V, V_{GS} = 0V, f = 1.0MHz$
Output Capacitance	C_{oss}	—	84	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	67	—	pF	
Gate Resistance	R_g	—	14.3	—	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$
Total Gate Charge ($V_{GS} = -4.5V$)	Q_g	—	11	—	nC	$V_{DS} = -10V, I_D = -3.7A$
Total Gate Charge ($V_{GS} = -8V$)		—	18	—	nC	
Gate-Source Charge	Q_{gs}	—	1.5	—	nC	
Gate-Drain Charge	Q_{gd}	—	2.3	—	nC	
Turn-On Delay Time	$t_{D(on)}$	—	5.0	—	ns	$V_{DD} = -10V, V_{GS} = -4.5V, R_L = 3.3\Omega, R_G = 1\Omega$
Turn-On Rise Time	t_r	—	9.5	—	ns	
Turn-Off Delay Time	$t_{D(off)}$	—	29.7	—	ns	
Turn-Off Fall Time	t_f	—	20.4	—	ns	
Body Diode Reverse Recovery Time	t_{rr}	—	23.6	—	nS	$I_S = -3.0A, di/dt = 100A/\mu s$
Body Diode Reverse Recovery Charge	Q_{rr}	—	11.4	—	nC	$I_S = -3.0A, di/dt = 100A/\mu s$

Notes: 6. Short duration pulse test used to minimize self-heating effect.
7. Guaranteed by design. Not subject to product testing.

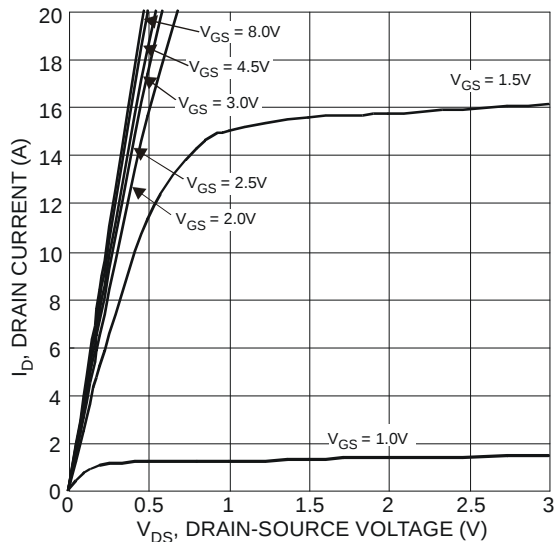


Figure 1 Typical Output Characteristics

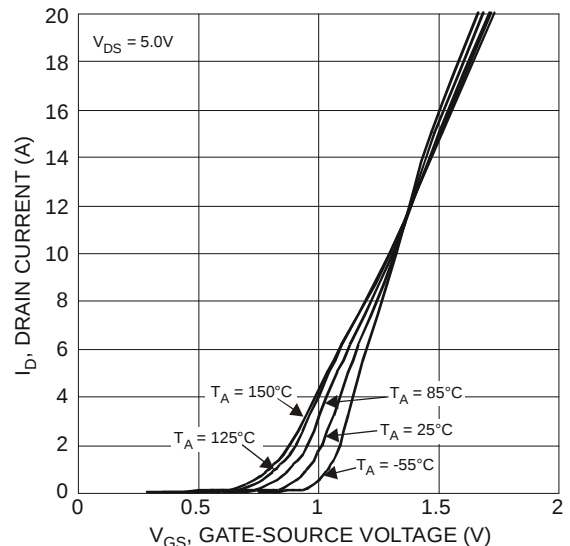


Figure 2 Typical Transfer Characteristics

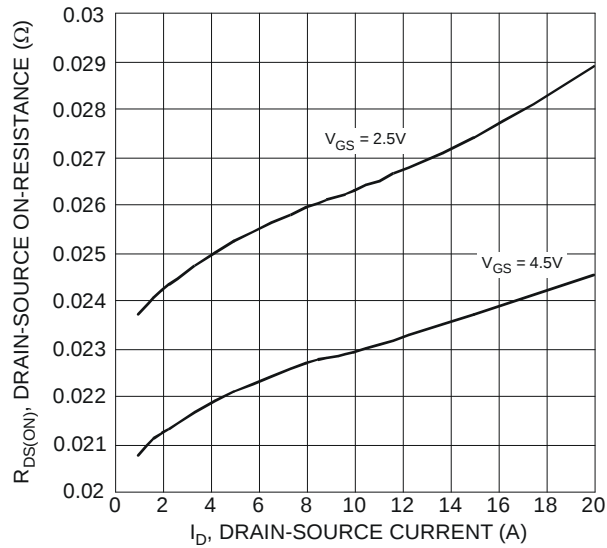


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

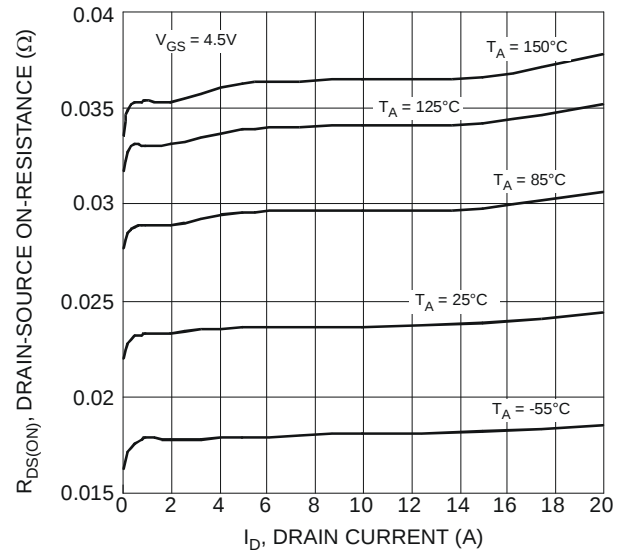


Figure 4 Typical On-Resistance vs. Drain Current and Temperature

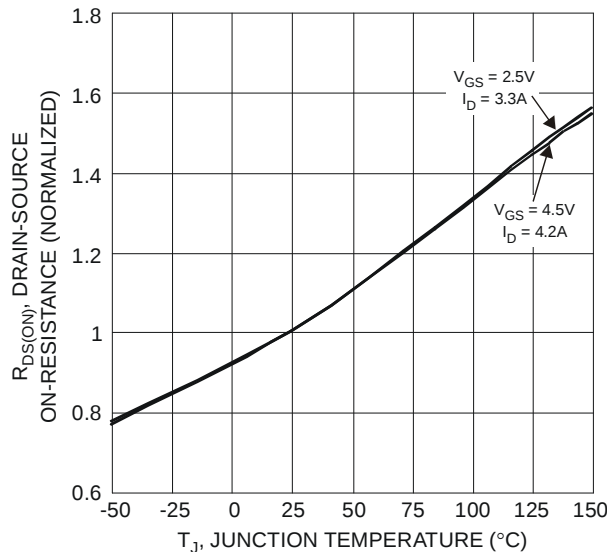


Figure 5 On-Resistance Variation with Temperature

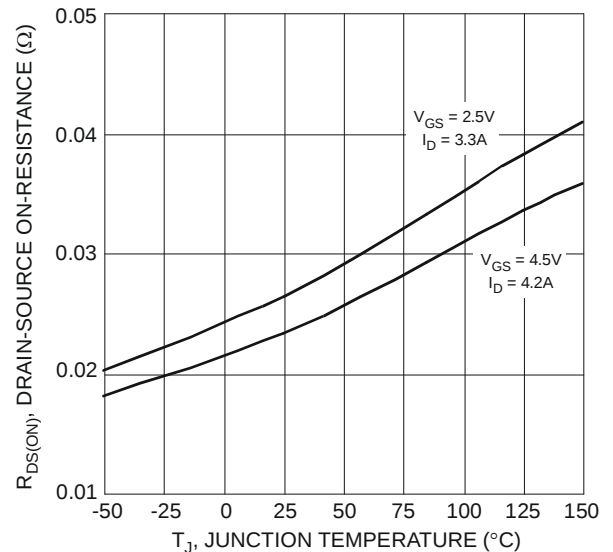


Figure 6 On-Resistance Variation with Temperature

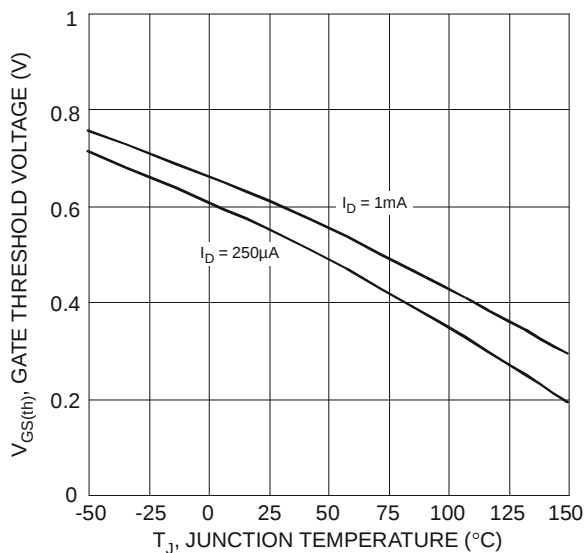


Figure 7 Gate Threshold Variation vs. Ambient Temperature

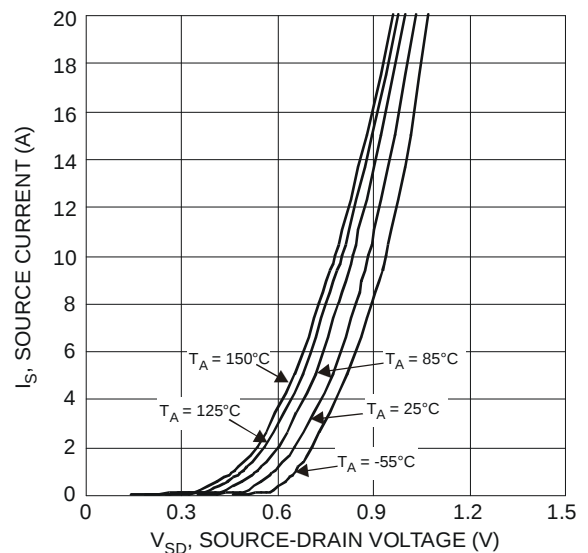


Figure 8 Diode Forward Voltage vs. Current

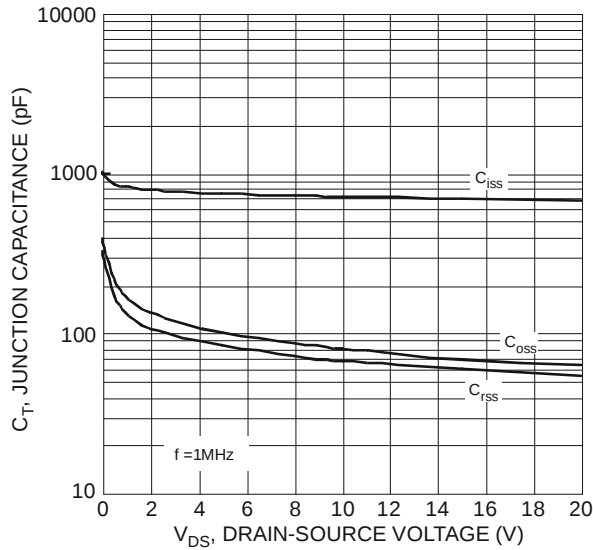


Figure 9 Typical Junction Capacitance

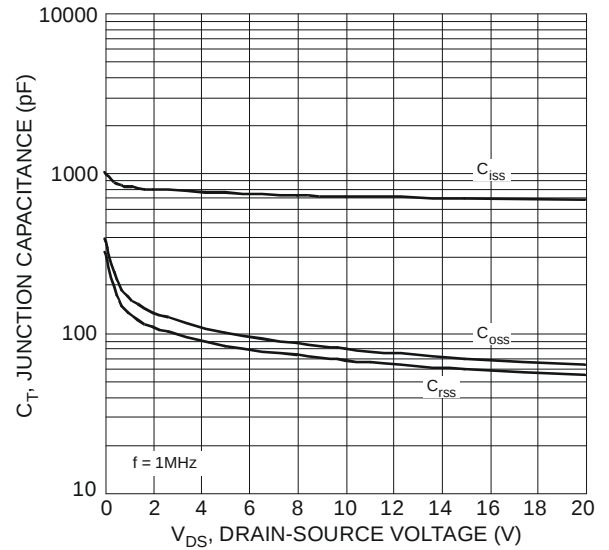


Figure 10 Typical Junction Capacitance

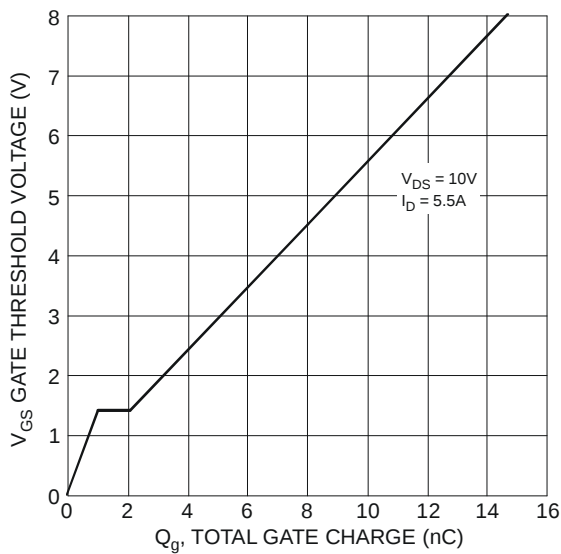


Figure 11 Gate Charge

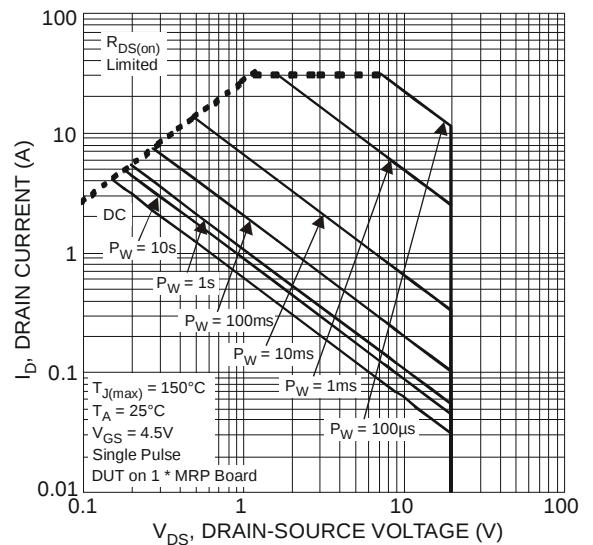


Figure 12 SOA, Safe Operation Area

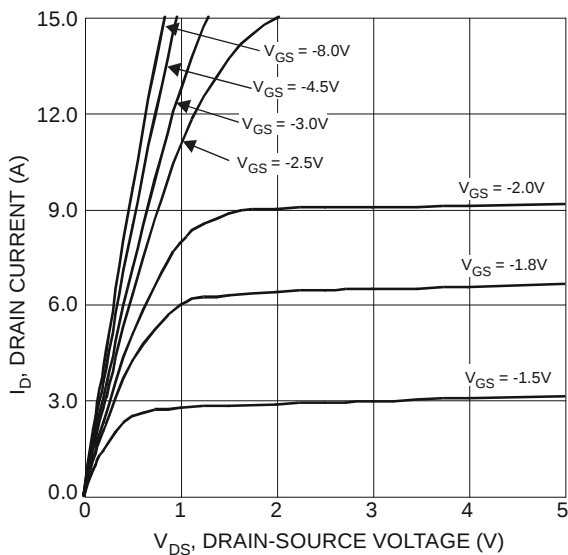


Figure 13 Typical Output Characteristics

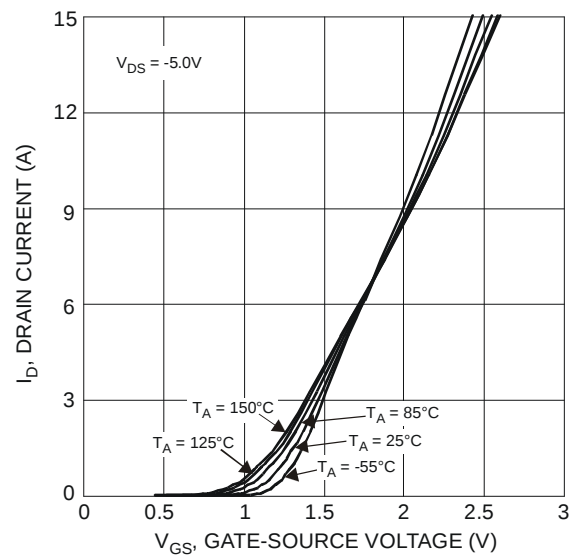


Figure 14 Typical Transfer Characteristics

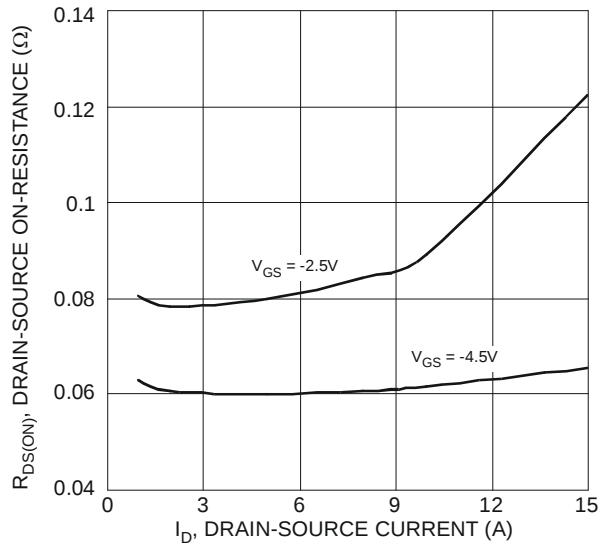


Figure 15 Typical On-Resistance vs. Drain Current and Gate Voltage

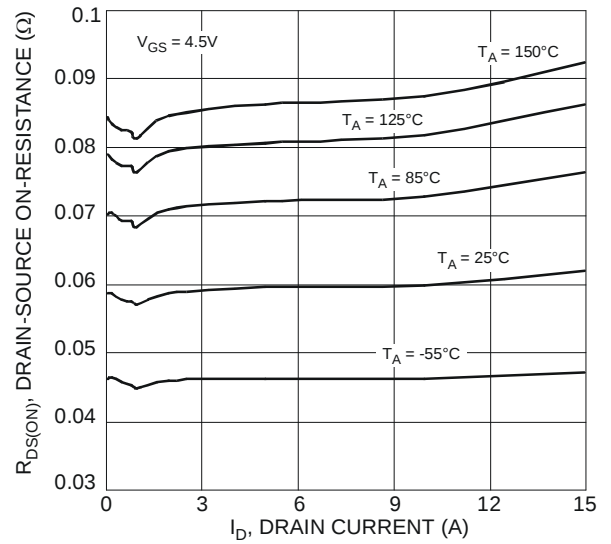


Figure 16 Typical On-Resistance vs. Drain Current and Temperature

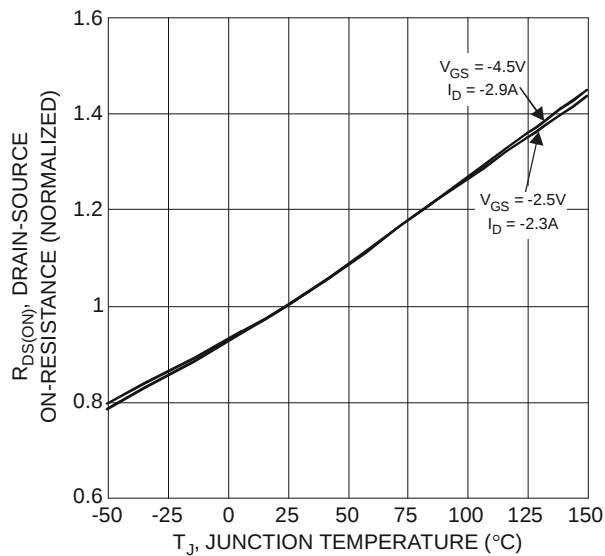


Figure 17 On-Resistance Variation with Temperature

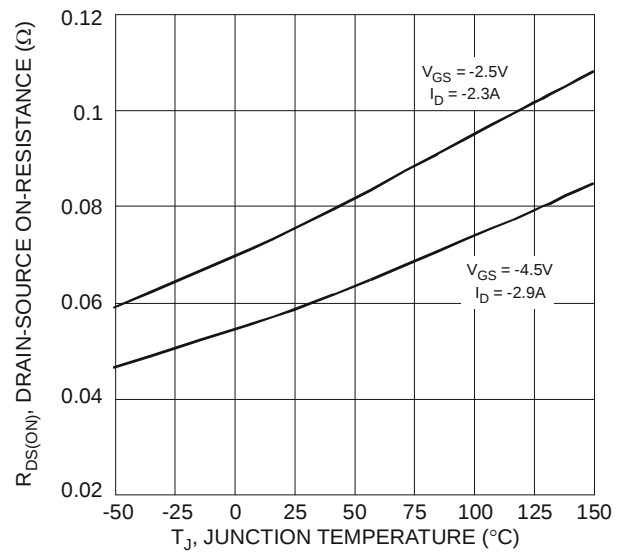


Figure 18 On-Resistance Variation with Temperature

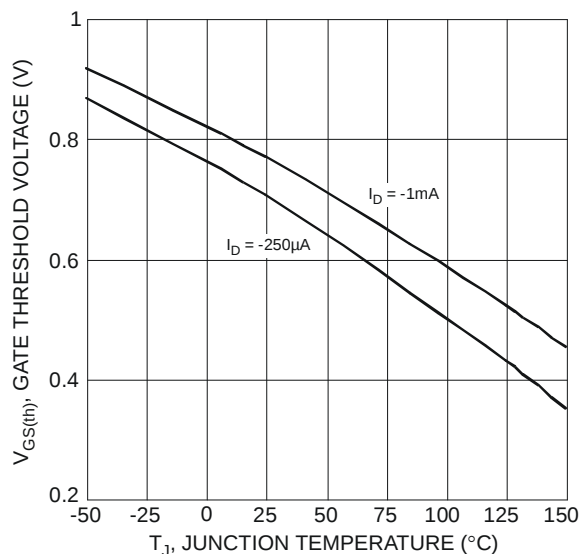


Figure 19 Gate Threshold Variation vs. Ambient Temperature

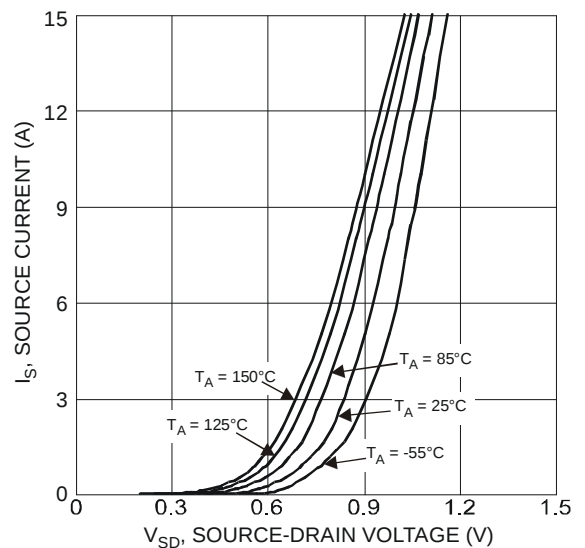


Figure 20 Diode Forward Voltage vs. Current

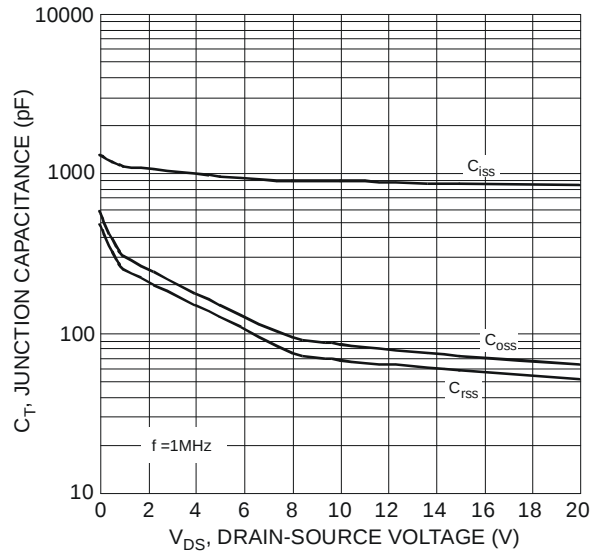


Figure 21 Typical Junction Capacitance

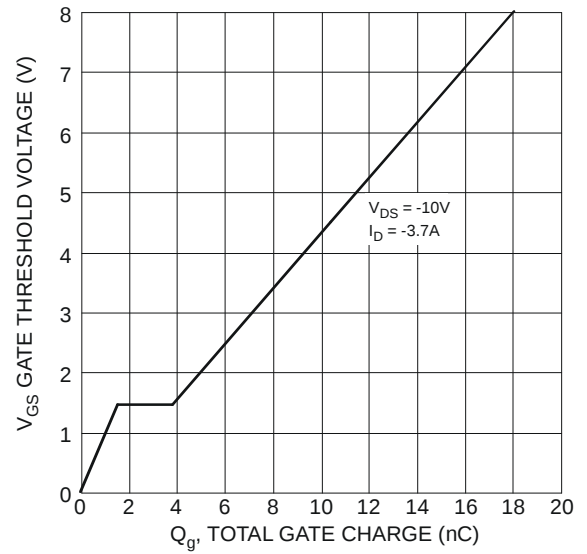


Figure 22 Gate Charge

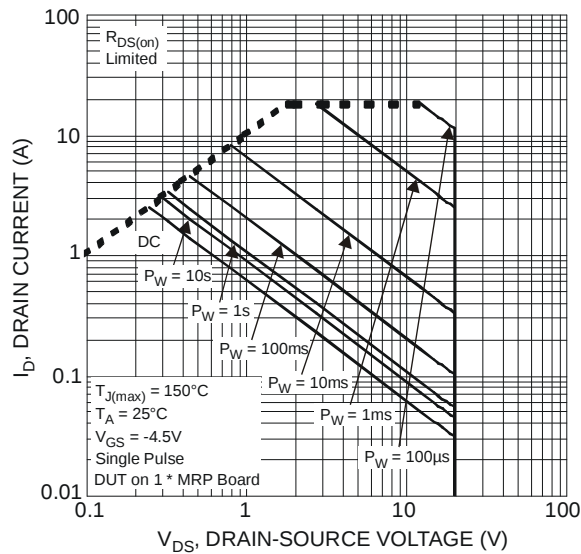


Figure 23 SOA, Safe Operation Area

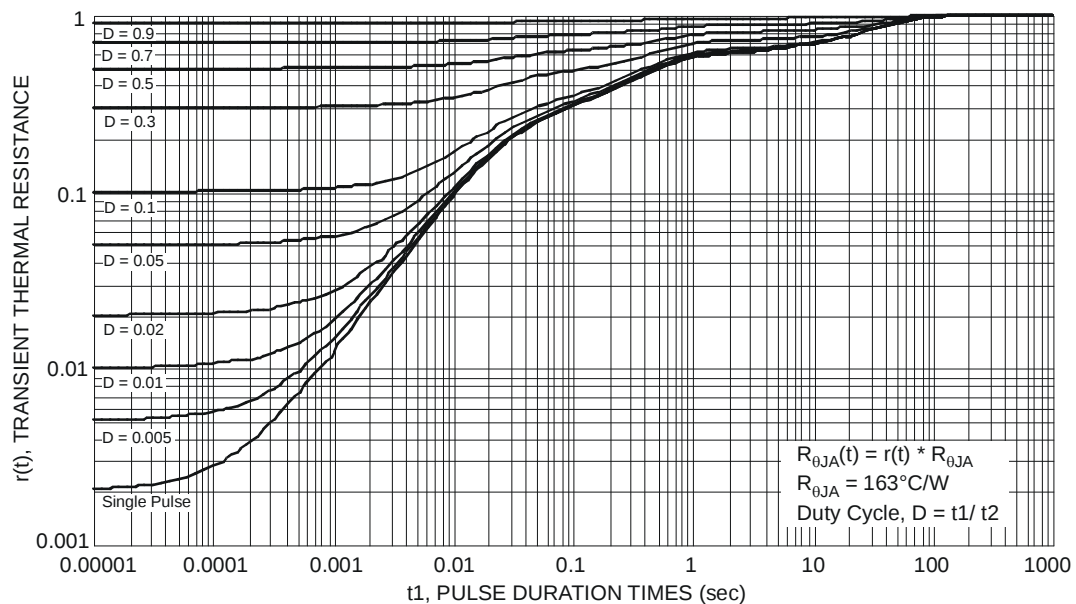
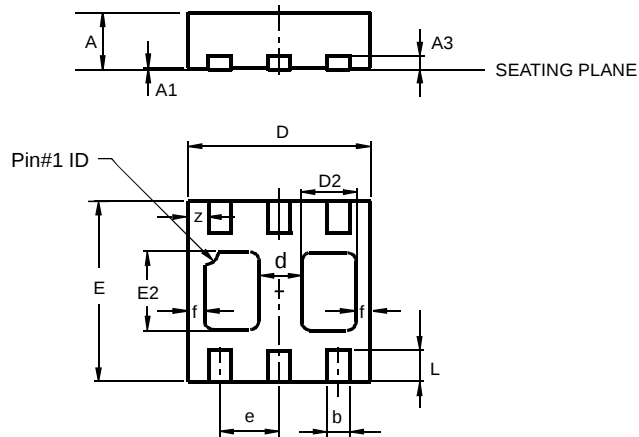


Figure 24 Transient Thermal Resistance

Package Outline Dimensions

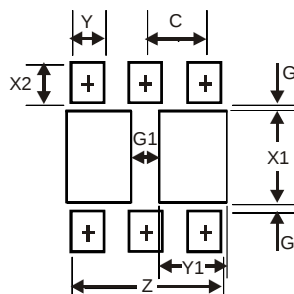
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the version.



U-DFN2020-6 Type B			
Dim	Min	Max	Typ
A	0.545	0.605	0.575
A1	0	0.05	0.02
A3	—	—	0.13
b	0.20	0.30	0.25
D	1.95	2.075	2.00
d	—	—	0.45
D2	0.50	0.70	0.60
e	—	—	0.65
E	1.95	2.075	2.00
E2	0.90	1.10	1.00
f	—	—	0.15
L	0.25	0.35	0.30
z	—	—	0.225
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	1.67
G	0.20
G1	0.40
X1	1.0
X2	0.45
Y	0.37
Y1	0.70
C	0.65

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